

Sumikon® EME-9300HX

Epoxy; Epoxide
Sumitomo Bakelite Co., Ltd.

Message:
EME-9300H Series are low alpha particle epoxy molding compounds.

General Information			
Features	High purity		
	Fast curing		
Uses	Semiconductor molding compound		
Forms	Liquid		
Processing Method	Enclosure		
Physical	Nominal Value	Unit	Test Method
Specific Gravity	1.82	g/cm ³	ASTM D792
Water Absorption (24 hr)	0.30	%	ASTM D570
Mechanical	Nominal Value	Unit	Test Method
Flexural Modulus (25°C)	11800	MPa	ASTM D790
Flexural Strength (25°C)	118	MPa	ASTM D790
Thermal	Nominal Value	Unit	Test Method
Glass Transition Temperature	165	°C	ASTM E1356
Thermal Conductivity	0.67	W/m/K	ASTM C177
Electrical	Nominal Value	Unit	Test Method
Volume Resistivity	1.0E+13	ohms·cm	ASTM D257
Thermoset	Nominal Value	Unit	
Demold Time (180°C)	0.50 - 1.0	min	
Post Cure Time (175°C)	4.0 - 10	hr	
Additional Information			

Spiral Flow, SB-U-03-003: 51 cmGel Time, SB-U-03-005, 175°C: 26 secThermal Expansion, SB-U-02-002, TTg: 6.8 E-5/°CFlexural Strength, SB-U-01-001, 240°C: 15.7 MPaFlexural Modulus, SB-U-01-002, 240°C: 637.5 MPaUL-94 Flame Class, SB-U-03-003: V-0Extracted Na+, SB-U-04-043: <1 ppmExtracted Cl-, SB-U-04-043: 5 ppmTransfer Pressure: 686.5-1177 MPa

The information and data on this page are provided by manufacturers and document providers. SHANGHAI SUSHENG assumes no legal liability. It is strongly recommended to verify all technical data with material suppliers before final material selection.All rights belong to the original authors. If any infringement occurs, please contact us immediately.

Recommended distributors for this material

Susheng Import & Export Trading Co.,Ltd.

Tel: +86 21 5895 8519
Phone: +86 13424755533
Email: sales@su-jiao.com
No. 215, Lianhe North Road, Fengxian District, Shanghai, China



WECHAT